



718N-7970

Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Chang et al.

Serial No.: 09/468,249

Filed: December 10, 1999

For: SEMICONDUCTOR DIE PACKAGE INCLUDING CUP-SHAPED LEADFRAME

Examiner: Rao, Shrinivas H.

Art Unit: 2814

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

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OCT 23 2003
TECHNOLOGY CENTER 2800

Dear Sir:

In response to the Office Action mailed July 14, 20023, for the above captioned patent application, Applicants respectfully request entry of the following amendments and consideration of the following remarks.

Serial No.: 09/468,249